TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π -MOSV)

2SK2991

DC–DC Converter Relay Drive and Motor Drive Applications

- Low drain-source ON resistance $: RDS (ON) = 1.35 \Omega (typ.)$
- High forward transfer admittance $|Y_{fs}| = 4.0 \text{ S (typ.)}$
- Low leakage current $: I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 500 \ V)$
- Enhancement mode $: V_{th} = 2.0 \sim 4.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{ ID} = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	500	V	
Drain-gate voltage (R	_{GS} = 20 kΩ)	V _{DGR}	500	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	5	A	
	Pulse (Note 1)	I _{DP}	20	А	
Drain power dissipation	n (Tc = 25°C)	PD	50	W	
Single pulse avalanche	e energy (Note 2)	E _{AS}	180	mJ	
Avalanche current		I _{AR}	5	А	
Repetitive avalanche e	nergy (Note 3)	E _{AR}	4	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature ra	ange	T _{stg}	-55~150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

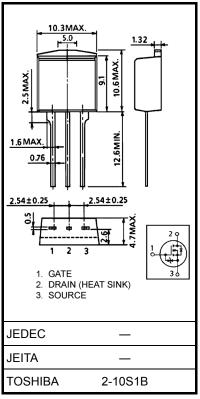
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	2.5	°C / W
Thermal resistance, channel to ambient	R _{th (ch−a)}	83.3	°C / W

Note 1: Ensure that the channel temperature does not exceed 150°C.

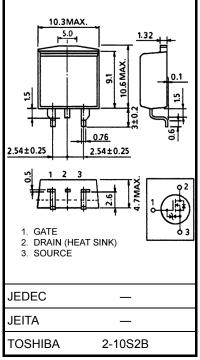
Note 2: V_DD = 90 V, T_{ch} = 25 $^{\circ}$ C (initial), L = 12.2 mH, R_G = 25 $\Omega,$ I_AR = 5 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.



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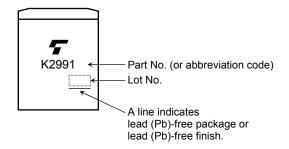
Electrical Characteristics (Ta = 25°C)

Charao	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	IGSS	V_{GS} = ±25 V, V_{DS} = 0 V	_	_	±10	μA
Gate-source bro	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30		_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 500 V, V _{GS} = 0 V	-	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	500	_	_	V
Gate threshold v	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0		4.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 2.5 A	_	1.35	1.50	Ω
Forward transfe	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 2.5 A	2.5	4.0	_	S
Input capacitance	ce	C _{iss}		_	780	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		60	—	pF
Output capacitance		C _{oss}			200	_	
Switching time	Rise time	tr	$v_{GS} \stackrel{10V}{_{0V}} \prod_{\substack{D = 2.5A \\ 0V}} v_{OUT}$	_	12	_	
	Turn-on time	t _{on}		_	25	_	20
	Fall time	t _f		_	15	_	ns
	Turn-off time	t _{off}	$V_{DD} \rightleftharpoons 225 V$ Duty $\leq 1\%$, t _w =10 μ s	_	60	_	
Total gate charge (gate-source plus gate-drain)		Qg			17	_	
Gate-source charge		Q _{gs}	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 5 A		11	—	nC
Gate-drain ("miller") charge		Q _{gd}		—	6	—	

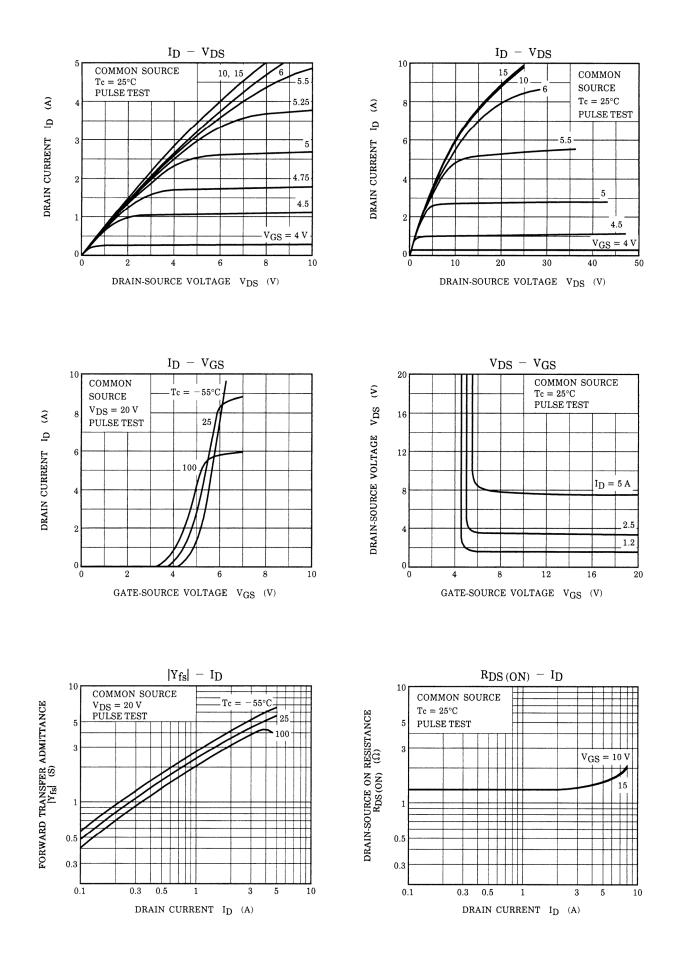
Source–Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	5	A
Pulse drain reverse current (Note 1)	I _{DRP}	—	_	_	20	A
Forward voltage (diode)	V _{DSF}	I _{DR} = 5 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 5 A, V _{GS} = 0 V, dI _{DR} / dt = 100 A / μs	_	1400		ns
Reverse recovery charge	Q _{rr}	$10R = 3 \Lambda$, $VGS = 0 V$, $UDR / UI = 100 \Lambda / \mu s$	_	9	_	μC

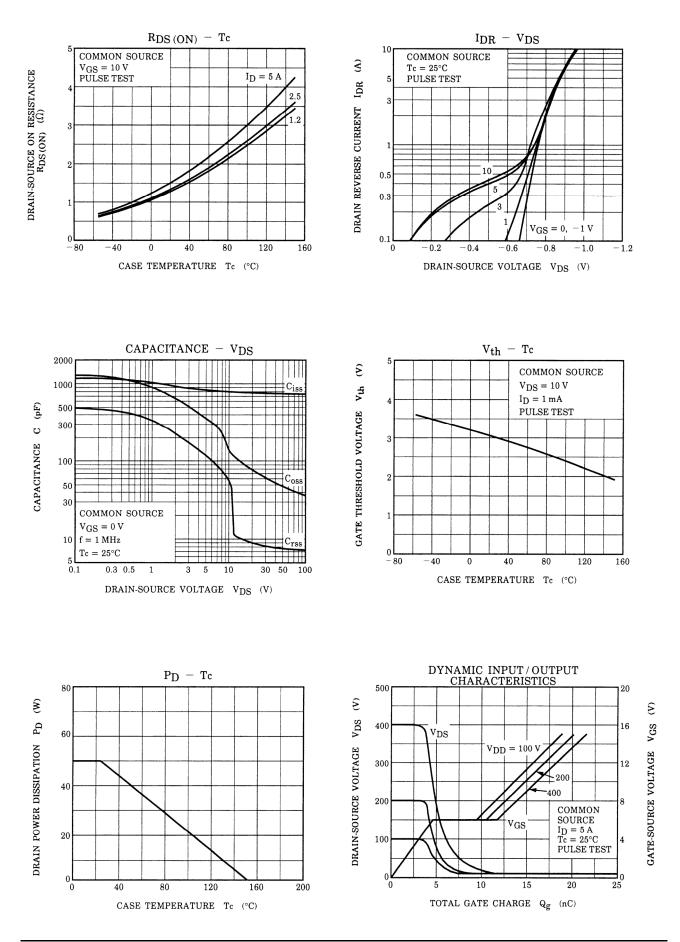
Marking

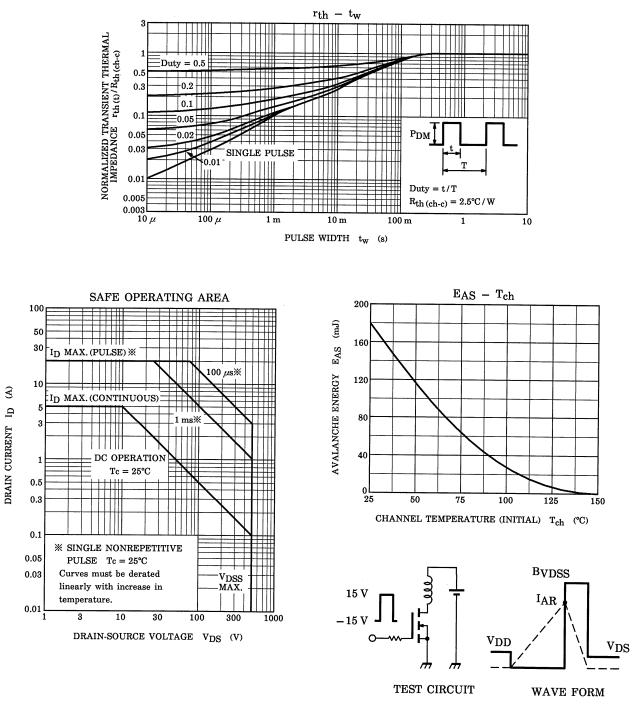


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